## WHAT IS CLAIMED IS:

10

15

Fr. C. III E. E.

1. A semiconductor light emitting device comprising:

nitride-based semiconductor layer including emission layer; and

a dielectric film formed on the surface of said nitride-based semiconductor layer, wherein

said dielectric film contains a nitride on the side of interface between said dielectric film and said nitride-based semiconductor layer while containing an oxide on the side opposite to said nitride-based semiconductor layer.

The semiconductor light emitting device according 2. to claim 1, wherein

said dielectric film successively includes a nitride film and an oxide film as said nitride and said oxide.

- The semiconductor light emitting device according 3: to claim 2, wherein
- said dielectric film further includes a compound film 20 containing nitrogen and oxygen between said nitride film and said oxide film.
- The semiconductor light emitting device according 4. to claim 3, wherein 25

5

20

said compound film has such a graded composition that the content of nitrogen gradually reduces and the content of oxygen gradually increases from the side of the interface between said compound film and said nitride film toward the side of the interface between said compound film and said oxide film.

5. The semiconductor light emitting device according to claim 2, wherein

said nitride film is a silicon nitride film or a titanium nitride film, and said oxide film is a silicon oxide film or a titanium oxide film.

6. The semiconductor light emitting device according to claim 1, wherein

said dielectric film includes a compound film containing nitrogen and oxygen as said nitride and said oxide, and said compound film has such a graded composition that the content of nitrogen gradually reduces and the content of oxygen gradually increases from the side of the interface between said compound film and said nitride-based semiconductor layer toward the opposite side.

7. The semiconductor light emitting device according to 25 claim 6, wherein

said compound film is a compound film containing silicon or titanium and containing nitrogen and oxygen.

Yor

- 8. A semiconductor light emitting device comprising:
- a nitride-based semiconductor layer including an emission layer; and
- a dielectric film formed on the surface of said nitride-based semiconductor layer, wherein

said dielectric film contains a compound containing nitrogen and oxygen on the side of the interface between said dielectric film and said nitride-based semiconductor layer while containing an oxide on the side opposite to said nitride-based semiconductor layer.

15

20

10

9. The semiconductor light emitting device according to claim 8, wherein

said dielectric film includes a compound film as said compound and includes an oxide film as said oxide, while said compound film has such a graded composition that the content of nitrogen gradually reduces and the content of oxygen gradually increases from the side of the interface between said compound film and said nitride-based semiconductor layer toward the opposite side.

25

10. The semiconductor light emitting device according

to claim 9, wherein

said compound film is a compound film containing silicon or titanium and containing nitrogen and oxygen, and said oxide film is a silicon oxide film or a titanium oxide film.

5

10

15

20

11. A semiconductor light emitting device comprising:

a nitride-based semiconductor layer including an emission layer; and

a dielectric film formed on the surface of said nitride-based semiconductor layer, wherein

said dielectric film contains a nitride on the side of the interface between said dielectric film and said nitride-based semiconductor layer while containing a compound containing nitrogen and oxygen on the side opposite to said nitride-based semiconductor layer.

12. The semiconductor light emitting device according to claim 11, wherein

said dielectric film includes a nitride film as said nitride and includes a compound film as said compound, and said compound film has such a graded composition that the content of nitrogen gradually reduces and the content of oxygen gradually increases from the side of the interface between said compound film and said nitride film toward the opposite side.

The thing the ten then then

5

10

15

13. The semiconductor light emitting device according to claim 12, wherein

said nitride film is a silicon nitride film or a titanium nitride film, and said compound film is a compound film containing silicon or titanium and containing nitrogen and oxygen.

14. The semiconductor light emitting device according to claim 1, wherein

said nitride-based semiconductor layer further includes a cladding layer formed on said emission layer, said cladding layer has a flat portion and a ridge portion located on said flat portion, and said dielectric film is formed on said flat portion of said cladding layer and the side surface of said ridge portion.

15. The semiconductor light emitting device according to claim 14, wherein

the side surface of said ridge portion is irregularized,
and said dielectric film is formed on said flat portion of said
cladding layer and the side surface of said ridge portion.

- 16. The semiconductor light emitting device according to claim 1, wherein
- 25 said nitride-based semiconductor layer further includes

20

5

a first conductivity type semiconductor layer provided under conductivity type second emission layer and а said semiconductor layer provided on said emission layer, a partial region of said nitride-based semiconductor layer is removed to partially expose said first conductivity type semiconductor layer, a first electrode is formed on said exposed region of said first conductivity type semiconductor layer, a second formed on said second conductivity type electrode semiconductor layer, and said dielectric film is formed on the surface of said nitride-based semiconductor layer between said first electrode and said second electrode.

- 17. A semiconductor light emitting device comprising:

  an emission layer composed of a nitride-based

  15 semiconductor;
  - a cladding layer formed on said emission layer and composed of a nitride-based semiconductor having a flat portion and a ridge portion located on said flat portion; the side surface of said ridge portion of said cladding layer being irregularized, and
  - a dielectric film formed on said flat portion of said cladding layer and the side surface of said ridge portion.
- 18. The semiconductor light emitting device according 25 to claim 17, wherein

said dielectric film contains a nitride on the side of the interface between said dielectric film and said nitride-based semiconductor layer while containing an oxide on the side opposite to said nitride-based semiconductor layer.

5

10

20

19. The semiconductor light emitting device according to claim 17, wherein

said dielectric film contains a compound containing nitrogen and oxygen on the side of the interface between said dielectric film and said nitride-based semiconductor layer while containing an oxide on the side opposite to said nitride-based semiconductor layer.

20. The semiconductor light emitting device according 15 to claim 17, wherein

said dielectric film contains a nitride on the side of the interface between said dielectric film and said nitride-based semiconductor layer while containing a compound containing nitrogen and oxygen on the side opposite to said nitride-based semiconductor layer.